

*Proposed*PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Application No.: 09/991,931

Filed: November 26, 2001

Group Art Unit: 2823

Examiner: H. Lee

Docket No.: 103092.02

For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING
THE SAME, CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

FAX RECEIVED

AMENDMENT UNDER 37 C.F.R. §1.111

FEB 19 2003

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

TECHNOLOGY CENTER 2800

Sir:

In reply to the December 13, 2002 Office Action, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 25, lines 17-23, delete current paragraph and insert therefor:

In this way, after the penetrating holes 214a are formed, the conductive member 118 is formed on the substrate 214, to constitute two-layer substrate. For example, if the substrate 214 is of a thermoplastic substance, it can be softened by heating, and a conductive foil adhered without the use of adhesive, and by etching thereof a conductive member 118 can be formed. Alternatively, sputtering may equally be applied.

IN THE CLAIMS:

Please replace claims 53, 70 and 71 as follows:

53. (Amended) A substrate having penetrating holes formed therein, the substrate having a conductive member adhered on one side thereof by an adhesive material over a